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(54) FINGERPRINT SENSOR AND TERMINAL USING THE SAME

FINGERABDRUCKSENSOR UND ENDGERÄT MIT VERWENDUNG DAVON

CAPTEUR D'EMPREINTES DIGITALES ET TERMINAL L'UTILISANT

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(56) References cited:

WO-A1-2016/036046 CN-A- 101 131 945
CN-A- 105 825 165 DE-A1-102013 005 500
US-A1- 2011 309 482

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Description

TECHNICAL FIELD

[0001] The present disclosure relates to terminals, and particularly to a fingerprint sensor and a terminal using the same.

BACKGROUND

[0002] A fingerprint sensor may generally include a chip assembly and a protection assembly. The protection assembly can protect the chip assembly, and increase the rigidity of the chip assembly, so that it is convenient to mount the fingerprint sensor in the terminal. The chip assembly may include an outer surface and an inner surface. The outer surface is exposed outside of the terminal, so that the outer surface can be touched. The protection element generally covers the outer surface or the inner surface, which may increase the thickness of the fingerprint sensor, so that the fingerprint sensor may not be suitable for a thin terminal.

[0003] WO 2016/036046 A1 relates to a fingerprint sensor module that can have an improved waterproof function and a manufacturing method therefor. The fingerprint sensor module includes a fingerprint sensor, a main substrate, and a conductive resin arranged between the fingerprint sensor and the main substrate to seal the fingerprint sensor and the main substrate.

[0004] DE 102013005500 A1 relates to a fingerprint sensor including a conductive layer receivable within a housing of an electronic device.

[0005] US 2011/0309482 A1 relates to a fingerprint sensor which may include an encapsulating material on a finger sensing IC and covering the finger sensing area, and a bezel adjacent the finger sensing area and on an uppermost surface of the encapsulating layer.

[0006] CN 105825165A relates to a fingerprint identification module, a terminal device, and an assembling method. The fingerprint identification module includes a fingerprint chip, a fingerprint cover plate, a flexible circuit board, a reinforcing plate, and a decorative ring arranged at the periphery of the fingerprint chip.

[0007] CN101131945A relates to a manufacturing method for a chip packaging structure. A packaging material layer is formed on a surface of a substrate. A film is attached on a surface of the packaging material layer. A first cutting tool penetrates into the substrate and the packaging material along a cutting line, and a second cutting tool penetrates into the substrate along part of the cutting line to expose part of the packaging material layer.

SUMMARY

[0008] Embodiments of the present disclosure provide a fingerprint sensor and a terminal using the same, which can reduce the thickness of the fingerprint sensor.

[0009] According to a first aspect, a fingerprint sensor as set out in claim 1 is provided. The fingerprint sensor includes a chip assembly and a protection assembly. The chip assembly includes a circuit board and a sealing element laminated on the circuit board. The protection assembly includes a first protection element. The protection assembly surrounds at least a portion of the peripheral side of the chip assembly. The circuit board protrudes from the sealing element. The sealing element includes a limitation surface surrounding the circuit board. A shape of the limitation surface is the same as that of the first protection element, where the limitation surface of the sealing element is engaged with the first protection element to define a space to receive the circuit board.

[0010] According to a second aspect, a fingerprint sensor as set out in claim 6 is provided. The fingerprint sensor includes a chip assembly and a protection assembly. The chip assembly includes a circuit board and a sealing element laminated on the circuit board. The protection assembly includes a first protection elements. The protection assembly surrounds at least a portion of the peripheral side of the chip assembly. The sealing element protrudes from the circuit board. The circuit board includes a limitation surface surrounding the sealing element. A shape of the limitation surface is the same as that of the first protection element, where the limitation surface of the circuit board is engaged with the first protection element to define a space to receive the sealing element.

[0011] According to a third aspect, a terminal as set out in claim 8 is provided. The terminal includes a housing and a fingerprint sensor of either the first or second aspect discussed above.

[0012] In the present disclosure, the fingerprint sensor is not thick due to the protection assembly, so that the fingerprint sensor is suitable for a thin terminal.

BRIEF DESCRIPTION OF THE DRAWINGS

[0013] In order to illustrate the technical solutions of the embodiments of the present disclosure more clearly, the drawings used in the description of the embodiments will be briefly described, it will be apparent that the drawings described in the following are embodiments of the present disclosure, and it will be apparent to those skilled in the art that other drawings can be obtained from the drawings without any creative work.

FIG. 1 is a structural view of a terminal in accordance with an embodiment of the present disclosure, illustrating that a fingerprint sensor is exposed outside of a rear cover of the fingerprint sensor.

FIG. 2 is a structural view of a terminal in accordance with another embodiment of the present disclosure, illustrating that the fingerprint sensor is exposed outside of a front surface of the terminal.

FIG. 3 is a perspective view of a fingerprint sensor in accordance with an embodiment of the present disclosure.

FIG. 4 is a perspective view of a chip assembly of the fingerprint sensor of FIG. 3.

FIG. 5 is a perspective view of the chip assembly of the fingerprint sensor of FIG. 3, viewed from another viewpoint.

FIG. 6 is an exploded view of the fingerprint sensor of FIG. 3.

FIG. 7 is a sectional view of the fingerprint sensor of FIG. 3.

FIG. 8 is an exploded view of the fingerprint sensor of FIG. 7.

FIG. 9 is a perspective view of a fingerprint sensor in accordance with another embodiment of the present disclosure.

FIG. 10 is a perspective view of a chip assembly of the fingerprint sensor of FIG. 9.

FIG. 11 is a perspective view of the chip assembly of the fingerprint sensor of FIG. 9, viewed from another viewpoint.

FIG. 12 is an exploded view of the fingerprint sensor of FIG. 9.

FIG. 13 is a sectional view of the fingerprint sensor of FIG. 9.

FIG. 14 is an exploded view of the fingerprint sensor of FIG. 13.

FIG. 15 is a flow chart of a method for manufacturing a fingerprint sensor in accordance with an embodiment of the present disclosure.

DETAILED DESCRIPTION OF ILLUSTRATED EMBODIMENTS

[0014] Embodiments of the present disclosure will be described in detail in the following descriptions, examples of which are shown in the accompanying drawings, in which the same or similar elements and elements having same or similar functions are denoted by like reference numerals throughout the descriptions. The embodiments described herein with reference to the accompanying drawings are explanatory and illustrative, which are just used to illustrate the present disclosure, and shall not be construed to limit the present disclosure.

[0015] In the description of the present disclosure, it is to be understood that orientations or position relationships illustrated by terms such as "central," "longitudinal," "lateral," "length," "width," "thickness," "upper," "lower," "front," "rear," "left," "right," "vertical," "horizontal," "top," "bottom," "inner," "outer," "clockwise," and "counter-clockwise" are based on orientation or position relationship based on the accompanying drawings, and are not used to indicate or imply the devices or elements must have specific orientations, and must be constructed and operated in specific orientations, and shall not be construed to limit the present disclosure. In addition, terms such as "first" and "second" are used herein for purposes of description and are not intended to indicate or imply relative importance or significance or to imply the number of indicated technical features. Thus, the fea-

ture defined with "first" and "second" may include one or more of this feature. In the description of the present disclosure, "a plurality of" or "a number of" means two or more than two, unless specified otherwise.

[0016] In the present disclosure, unless specified or limited otherwise, the terms "mounted," "connected," "coupled," and the like are used broadly, and may be, for example, fixed connections, detachable connections, or integral connections; may also be mechanical or electrical connections; may also be direct connections or indirect connections via intervening structures; may also be inner communications of two elements or mutual interaction relationship between two elements. Those skilled in the art can understand specific meaning of the above terms in the present disclosure according to specific situations.

[0017] In the present disclosure, unless specified and limited otherwise, a first feature "on" or "below" a second feature may include that the first feature is in direct contact with the second feature, and may also include that the first feature and the second feature are not in direct contact with each other, but are contacted via an additional feature formed therebetween. Furthermore, the first feature "on," "above," or "on top of" a second feature may include that the first feature is right or obliquely "on," "above," or "on top of" the second feature, or just means that the first feature is at a height higher than that of the second feature. The first feature "below," "under," or "on bottom of" the second feature may include that the first feature is right or obliquely "below," "under," or "on bottom of" the second feature, or just means that the first feature is at a height lower than that of the second feature.

[0018] Various embodiments and examples are provided in the following description to implement different structures of the present disclosure. In order to simplify the present disclosure, elements and settings of specific examples will be described. Certainly, these elements and settings are only examples and are not intended to limit the present disclosure. In addition, reference numerals may be repeated in different examples of the present disclosure. This repeating is for the purpose of simplification and clarity and does not refer to relations between different embodiments and/or settings. Furthermore, examples of different processes and materials are provided in the present disclosure. However, it would be appreciated by those skilled in the art that other processes and/or materials may be also applied.

[0019] The following will further illustrate embodiments of the present disclosure in detail in combination with the accompanying drawings.

[0020] Terminals illustrated in embodiments of the present disclosure may be mobile terminals or fixed terminals. The mobile terminals may be mobile phones, tablet computers, on-board computers, and so on. The fixed terminals may be desktop computers, automatic teller machines, and so on.

[0021] FIG. 1 is a structural view of a terminal in ac-

cordance with an embodiment of the present disclosure. A terminal 1000 may include a fingerprint sensor 1001. The fingerprint sensor 1001 is exposed outside of a rear cover 1002 of the terminal 1000. The rear cover 1002 may define a through hole (not indicated) to expose the fingerprint sensor 1001 outside of the rear cover 1002. A user can touch the fingerprint sensor 1001 to input an instruction, for example, an unlock instruction, an image photographing instruction, or the like. When the fingerprint sensor 1001 is exposed outside of the rear cover 1002 of the terminal 1000, the fingerprint sensor 1001 is generally arranged to be adjacent to a rear camera of the terminal 1000, so that it is convenient to touch the fingerprint sensor 1001. The fingerprint sensor 1001 may also be arranged on other positions, and the present disclosure is not limited thereto.

[0022] FIG. 2 is a structural view of a terminal in accordance with another embodiment of the present disclosure. A terminal 2000 may include a fingerprint sensor 2001. The fingerprint sensor 2001 is exposed outside of a front surface of the terminal 2000 where a display screen 2002 is located, that is, the fingerprint sensor 2001 is arranged on a position of a peripheral side surrounding the display screen 2002. When the fingerprint sensor 2001 is exposed outside of the front surface of the terminal 2000, the fingerprint sensor 2001 is generally located below the display screen 2002, so that it is convenient to touch the fingerprint sensor 2001. The fingerprint sensor 2001 may also be arranged on other positions, and the present disclosure is not limited thereto.

[0023] What is needed to be illustrated is that the fingerprint sensor 1001 may be a fingerprint sensor 100 or a fingerprint sensor 200 illustrated in the following descriptions, and the fingerprint sensor 2001 may be also the fingerprint sensor 100 or the fingerprint sensor 200 illustrated in the following descriptions.

[0024] FIG. 3 is a perspective view of a fingerprint sensor in accordance with an embodiment of the present disclosure. The fingerprint sensor 100 may include a chip assembly 11 and a protection assembly 12. The protection assembly 12 may surround a peripheral side of the chip assembly 11 to protect the chip assembly 11 and increase the rigidity of the fingerprint sensor 100, so that it is convenient to mount the fingerprint sensor 100. In the embodiment, the protection assembly 12 surrounds the whole peripheral side of the chip assembly 11. Certainly, it can be understood that in other embodiments the protection assembly 12 may surround a portion of the peripheral side of the chip assembly 11, for example, a half of the peripheral side of the chip assembly 11.

[0025] Referring to FIGS. 4-6, the chip assembly 11 may include a circuit board 111 and a sealing element 112 laminated on the circuit board 111. The sealing element 112 may be made from epoxy molding compound (EMC). The circuit board 111 protrudes from the sealing element 112. The sealing element 112 may include a limitation surface 1121 surrounding the circuit board 111. In the embodiment, the limitation surface 1121 is annular.

Certainly, in other embodiments, the limitation surface 1121 may be other shapes, and the present disclosure is not limited thereto.

[0026] The protection assembly 12 may include a first protection element 121 and a second protection element 122. The first protection element 121 is engaged with the limitation surface 1121 to surround the circuit board 111. In the embodiment, the first protection element 121 is annular. Certainly, in other embodiments, the first protection element 121 may be other shapes, what is needed is that the first protection element 121 can be engaged with the limitation surface 1121. The second protection element 122 protrudes from a side of the first protection element 121 away from the circuit board 111 and surrounds the whole peripheral side of the sealing element 112 or a portion of the peripheral side of the sealing element 112.

[0027] In the embodiment, the first protection element 121 is fixed to the limitation surface 1121 via an adhesive layer 13, so that the protection assembly 12 can be fixed to the chip assembly 11. Certainly, in other embodiments, the second protection element 122 may be fixed to the peripheral side of the sealing element 112, so that the protection assembly 12 can also be fixed to the chip assembly 11. Furthermore, the thickness of the first protection element 121 may be substantially the same as or less than that of the circuit board 111, or a sum of the thickness of the first protection element 121 and the thickness of the adhesive layer 13 may be substantially the same as or less than that of the circuit board 111, so that the first protection element 121 is not higher than the circuit board 111.

[0028] In the embodiment, the first protection element 121 is engaged with the limitation surface 1121 of the sealing element 112 surrounding the circuit board 111. Thus, the fingerprint sensor 100 is not thick due to the protection assembly 12, so that the fingerprint sensor 100 is suitable for a thin terminal.

[0029] Referring further to FIG. 7 and FIG. 8, the chip assembly 11 may further include a die 113. The sealing element 112 defines a receiving cavity 1122. The die 113 is received in the receiving cavity 1122 and electrically coupled to the circuit board 111. The die 113 may be fixed to the circuit board 111 via adhesive, and the die 113 is electrically coupled to bonding pads 1110.

[0030] In some embodiments, the receiving cavity 1122 may include an opening (not shown) away from the circuit board 111. That is, the sealing element 112 does not cover a surface of the die 113 away from the circuit board 111. Under this condition, the chip assembly 11 may further include a decoration layer (not indicated) covering the opening. The decoration layer may have a pattern to beautify the fingerprint sensor 200. Certainly, the fingerprint sensor 200 may also be protected by the decoration layer.

[0031] Referring to FIGS. 9-11, the fingerprint sensor 200 in accordance with another embodiment of the present disclosure may include a chip assembly 21 and

a protection assembly 22. A difference between the fingerprint sensor 100 and the fingerprint sensor 200 is that the sealing element 212 protrudes from the circuit board 211, and the circuit board 211 includes a limitation surface 2111 surrounding the sealing element 212. In the embodiment, the limitation surface 2111 is annular. Certainly, in other embodiments, the limitation surface 2111 may be other shapes, and the present disclosure is not limited thereto.

[0032] Referring further to FIGS. 12-14, the protection element 22 may include a first protection element 221 and a second protection element 222. The first protection element 221 is engaged with the limitation surface 2111 to surround the sealing element 212. Certainly, in other embodiments, the first protection element 221 may be other shapes, what is needed is that the first protection element 221 can be engaged with the limitation surface 2111. The second protection element 222 protrudes from a side of the first protection element 221 away from the sealing element 212 and surrounds the whole peripheral side of the circuit board 211 or a portion of the peripheral side of the circuit board 211.

[0033] In the embodiment, the first protection element 221 is fixed to the limitation surface 2111 via an adhesive layer 23, so that the protection assembly 22 can be fixed to the chip assembly 21. Certainly, in other embodiments, the second protection element 222 may be fixed to the peripheral side of the sealing element 212, so that the protection assembly 22 can also be fixed to the chip assembly 21. Furthermore, the thickness of the first protection element 221 may be substantially the same as or less than that of the circuit board 212, or a sum of the thickness of the first protection element 221 and the thickness of the adhesive layer 23 may be substantially the same as or less than that of the circuit board 211, so that the first protection element 221 is not higher than the circuit board 211.

[0034] In the embodiment, the first protection element 221 is engaged with the limitation surface 2111 of the circuit board 211 surrounding the sealing element 212. Thus, the fingerprint sensor 100 is not thick due to the protection assembly 12, so that the fingerprint sensor 100 is suitable for a thin terminal.

[0035] Furthermore, the chip assembly 21 may further include a die 213. The sealing element 212 defines a receiving cavity 2122. The die 213 is received in the receiving cavity 212 and electrically coupled to the circuit board 211. The die 213 may be fixed to the circuit board 211 via adhesive, and the die 213 is electrically coupled to bonding pads 2110.

[0036] In some embodiments, the receiving cavity 2122 may include an opening (not indicated) away from the circuit board 211. That is, the sealing element 212 does not cover a surface of the die 213 away from the circuit board 211. Under this condition, the chip assembly 21 may further include a decoration layer (not indicated) covering the opening. The decoration layer may have a pattern to beautify the fingerprint sensor 200. Certainly,

the fingerprint sensor 200 may also be protected by the decoration layer.

[0037] Certainly, in other embodiments, a protection assembly may be absent from a fingerprint sensor. The protection assembly may be a portion of a housing of a terminal having the fingerprint sensor, for example, the protection assembly and the housing may be integrally formed.

[0038] FIG. 15 is a flow chart of a method for manufacturing a fingerprint sensor in accordance with an embodiment of the present disclosure. The method may include the follows.

[0039] At block 001, a chip base is cut to acquire multiple chip assemblies. Each chip assembly may include a circuit board and a sealing element laminated on the circuit board.

[0040] At block 003, a peripheral side of the circuit board is cut off to expose a portion of the sealing element (that is, the limitation surface as described above).

[0041] At block 005, a protection assembly is mounted to cause the protection assembly to be engaged with the limitation surface of the sealing element.

[0042] In alternative embodiments, at block 003, the circuit board is not cut, and a peripheral side of the sealing element is cut off to expose a portion of the circuit board (the limitation surface described above). At block 005, the protection element is engaged with the limitation surface of the circuit board.

[0043] While the present disclosure has been described in detail above with reference to the exemplary embodiments, the scope of the present disclosure is not limited thereto. As will occur to those skilled in the art, the present disclosure is susceptible to various modifications and changes without departing from the principle of the present disclosure. Therefore, the scope of the present disclosure should be determined by the scope of the claims.

Claims

1. A fingerprint sensor comprising a chip assembly (11) and a protection assembly (12), wherein the chip assembly (11) comprises a circuit board (111) and a sealing element (112) laminated on the circuit board (111), and wherein the protection assembly (12) comprises a first protection element (121),
characterised in that:

the protection assembly (12) surrounds at least a portion of the peripheral side of the chip assembly (11);
the circuit board (111) protrudes from the sealing element (112);
the sealing element (112) comprises a limitation surface (1121) surrounding the circuit board (111); and
a shape of the limitation surface (1121) is the

same as that of the first protection element (121), wherein the limitation surface (1121) of the sealing element (112) is engaged with the first protection element (121) to define a space to receive the circuit board (111).

2. The fingerprint sensor of claim 1, wherein the protection assembly (12) further comprises a second protection element (122), the second protection element (122) protrudes from a side of the first protection element (121) away from the circuit board (111) and surrounds at least a portion of the peripheral side of the sealing element (112).

3. The fingerprint sensor of claim 1, wherein the fingerprint sensor further comprises an adhesive layer (13), the first protection element (121) is fixed to the limitation surface (1121) via the adhesive layer (13).

4. The fingerprint sensor of any of claims 1-3, wherein the first protection element (121) is annular.

5. The fingerprint sensor of any of claims 1-4, wherein the chip assembly (11) further comprises a die (113), the sealing element (112) defines a receiving cavity (1122), and the die (113) is received in the receiving cavity (1122) and electrically coupled to the circuit board (111).

6. A fingerprint sensor comprising a chip assembly (21) and a protection assembly (22), wherein the chip assembly (21) comprises a circuit board (211) and a sealing element (212) laminated on the circuit board (211), and the protection assembly (22) comprises a first protection element (221),
characterised in that:

the protection assembly (22) surrounds at least a portion of the peripheral side of the chip assembly (21);
the sealing element (212) protrudes from the circuit board (211);
the circuit board (211) comprises a limitation surface (2111) surrounding the sealing element (212), and
a shape of the limitation surface (2111) is the same as that of the first protection element (221), wherein the limitation surface (2111) of the circuit board (211) is engaged with the first protection element (221) to define a space to receive the sealing element (212).

7. The fingerprint sensor of claim 6, wherein the protection assembly (22) further comprises a second protection element (222), the second protection element (222) protrudes from a side of the first protection element (221) away from the sealing element (212) and surrounds at least a portion of the peripheral

side of the circuit board (211).

8. A terminal comprising a housing and a fingerprint sensor of any preceding claim.

Patentansprüche

1. Fingerabdrucksensor, umfassend eine Chipanordnung (11) und eine Schutzanordnung (12), worin die Chipanordnung (11) eine Leiterplatte (111) und ein Versiegelungselement (112), das auf die Leiterplatte (111) laminiert ist, umfasst, und worin die Schutzanordnung (12) ein erstes Schutzelement (121) umfasst,

dadurch gekennzeichnet, dass:

die Schutzanordnung (12) zumindest einen Teil der Umfangsseite der Chipanordnung (11) umgibt;
die Leiterplatte (111) aus dem Versiegelungselement (112) herausragt;
das Versiegelungselement (112) eine Begrenzungsfläche (1121) umfasst, die die Leiterplatte (111) umgibt; und
eine Form der Begrenzungsfläche (1121) dieselbe ist, wie die des ersten Schutzelements (121), worin die Begrenzungsfläche (1121) des Versiegelungselements (112) mit dem ersten Schutzelement (121) in Eingriff steht, um einen Raum zu definieren, um die Leiterplatte (111) aufzunehmen.

2. Fingerabdrucksensor gemäß Anspruch 1, wobei die Schutzanordnung (12) ferner ein zweites Schutzelement (122) umfasst, und das zweite Schutzelement (122) aus einer Seite des ersten Schutzelements (121) von der Leiterplatte (111) weg herausragt und zumindest einen Teil der Umfangsseite des Versiegelungselements (112) umgibt.

3. Fingerabdrucksensor gemäß Anspruch 1, worin der Fingerabdrucksensor ferner eine Kleberschicht (13) umfasst und das erste Schutzelement (121) über die Kleberschicht (13) an der Begrenzungsfläche (1121) befestigt ist.

4. Fingerabdrucksensor gemäß einem der Ansprüche 1 bis 3, worin das erste Schutzelement (121) ringförmig ist.

5. Fingerabdrucksensor gemäß einem der Ansprüche 1 bis 4, worin die Chipanordnung (11) ferner einen Nacktchip (113) umfasst, das Versiegelungselement (112) einen Aufnahmehohlraum (1122) definiert und der Nacktchip (113) vom Aufnahmehohlraum (1122) aufgenommen und elektrisch mit der Leiterplatte (111) gekoppelt ist.

6. Fingerabdrucksensor, umfassend eine Chipanordnung (21) und eine Schutzanordnung (22), worin die Chipanordnung (21) eine Leiterplatte (211) und ein Versiegelungselement (212), das auf die Leiterplatte (211) laminiert ist, umfasst, und die Schutzanordnung (22) ein erstes Schutzelement (221) umfasst, **dadurch gekennzeichnet, dass:**

die Schutzanordnung (22) zumindest einen Teil der Umfangsseite der Chipanordnung (21) umgibt;
das Versiegelungselement (212) aus der Leiterplatte (211) herausragt;
die Leiterplatte (211) eine Begrenzungsfläche (2111) umfasst, die das Versiegelungselement (212) umgibt; und
eine Form der Begrenzungsfläche (2111) dieselbe ist, wie die des ersten Schutzelements (221), worin die Begrenzungsfläche (2111) der Leiterplatte (211) mit dem ersten Schutzelement (221) in Eingriff steht, um einen Raum zu definieren, um das Versiegelungselement (212) aufzunehmen.

7. Fingerabdrucksensor gemäß Anspruch 6, worin die Schutzanordnung (22) ferner ein zweites Schutzelement (222) umfasst, das zweite Schutzelement (222) aus einer Seite des ersten Schutzelements (221) vom Versiegelungselement (212) weg herausragt und zumindest einen Teil der Umfangsseite der Leiterplatte (211) umgibt.
8. Anschluss, umfassend ein Gehäuse und einen Fingerabdrucksensor gemäß einem der vorhergehenden Ansprüche.

Revendications

1. Capteur d'empreinte digitale comprenant un ensemble de puce (11) et un ensemble de protection (12), l'ensemble de puce (11) comprenant une carte de circuit imprimé (111) et un élément d'étanchéité (112) stratifié sur la carte de circuit imprimé (111), et dans lequel l'ensemble de protection (12) comprend un premier élément de protection (121), **caractérisé en ce que :**

l'ensemble de protection (12) entoure au moins une partie du côté périphérique de l'ensemble de puce (11) ;
la carte de circuit imprimé (111) fait saillie à partir de l'élément d'étanchéité (112) ;
l'élément d'étanchéité (112) comprend une surface de limitation (1121) entourant la carte de circuit imprimé (111) ; et
une forme de la surface de limitation (1121) est identique à celle du premier élément de protec-

tion (121), dans lequel la surface de limitation (1121) de l'élément d'étanchéité (112) est mise en prise avec le premier élément de protection (121) pour définir un espace destiné à recevoir la carte de circuit (111).

2. Capteur d'empreinte digitale selon la revendication 1, dans lequel l'ensemble de protection (12) comprend en outre un second élément de protection (122), le second élément de protection (122) fait saillie à partir d'un côté du premier élément de protection (121) à distance de la carte de circuit imprimé (111) et entoure au moins une partie du côté périphérique de l'élément d'étanchéité (112).
3. Capteur d'empreinte digitale selon la revendication 1, dans lequel le capteur d'empreinte digitale comprend en outre une couche adhésive (13), le premier élément de protection (121) est fixé à la surface de limitation (1121) via la couche adhésive (13).
4. Capteur d'empreinte digitale selon l'une quelconque des revendications 1 à 3, dans lequel le premier élément de protection (121) est annulaire.
5. Capteur d'empreinte digitale selon l'une quelconque des revendications 1 à 4, dans lequel l'ensemble de puce (11) comprend en outre une matrice (113), l'élément d'étanchéité (112) définit une cavité de réception (1122), et la matrice (113) est reçue dans la cavité de réception (1122) et couplée électriquement à la carte de circuit imprimé (111).
6. Capteur d'empreinte digitale comprenant un ensemble de puce (21) et un ensemble de protection (22), dans lequel l'ensemble de puce (21) comprend une carte de circuit imprimé (211) et un élément d'étanchéité (212) stratifié sur la carte de circuit imprimé (211), et l'ensemble de protection (22) comprend un premier élément de protection (221), **caractérisé en ce que :**

l'ensemble de protection (22) entoure au moins une partie du côté périphérique de l'ensemble de puce (21) ;
l'élément d'étanchéité (212) fait saillie à partir de la carte de circuit imprimé (211) ;
la carte de circuit imprimé (211) comprend une surface de limitation (2111) entourant l'élément d'étanchéité (212), et
une forme de la surface de limitation (2111) est identique à celle du premier élément de protection (221), dans lequel la surface de limitation (2111) de la carte de circuit imprimé (211) est mise en prise avec le premier élément de protection (221) pour définir un espace destiné à recevoir l'élément d'étanchéité (212).

7. Capteur d'empreinte digitale selon la revendication 6, dans lequel l'ensemble de protection (22) comprend en outre un second élément de protection (222), le second élément de protection (222) fait saillie à partir d'un côté du premier élément de protection (221) distant de l'élément d'étanchéité (212) et entoure au moins une partie du côté périphérique de la carte de circuit imprimé (211). 5
8. Terminal comprenant un boîtier et un capteur d'empreinte digitale selon l'une quelconque des revendications précédentes. 10

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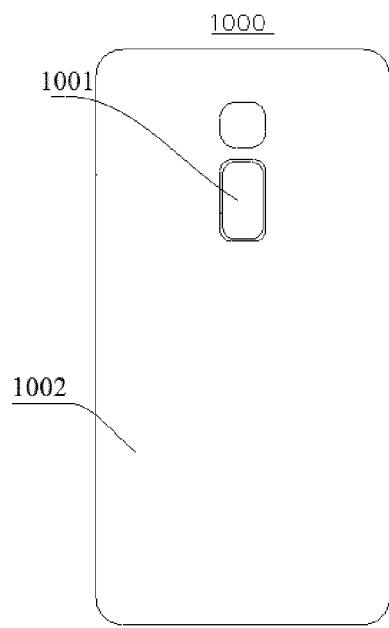


FIG. 1

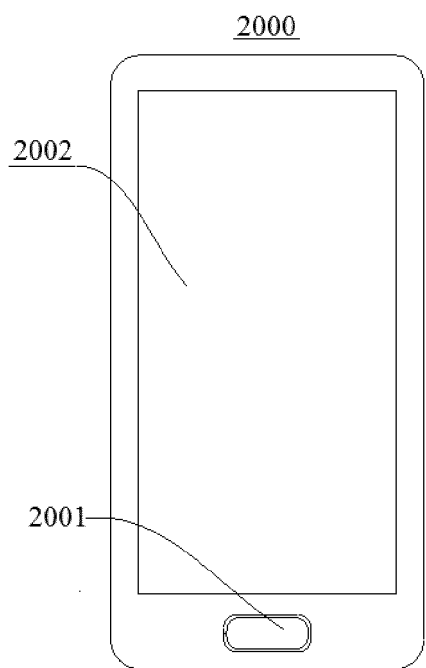


FIG. 2

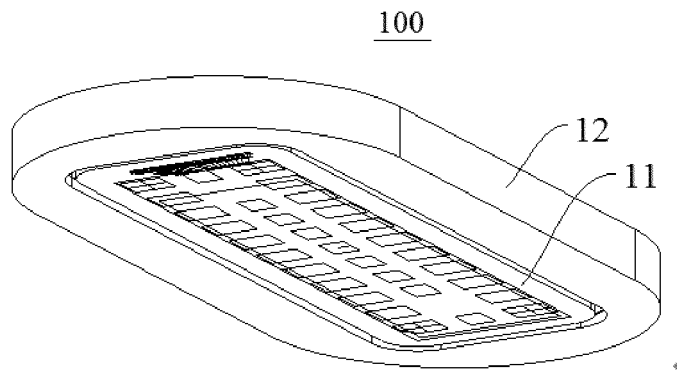


FIG. 3

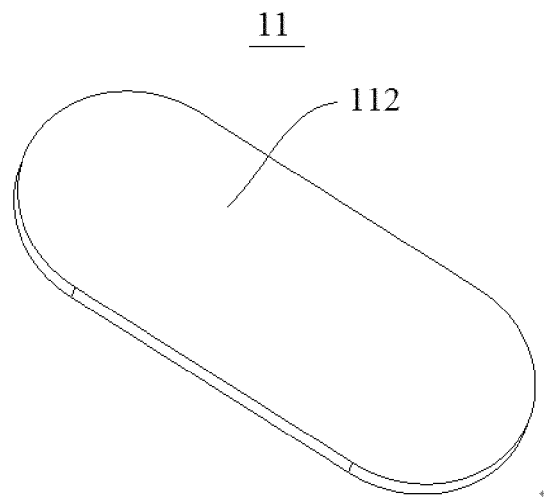


FIG. 4

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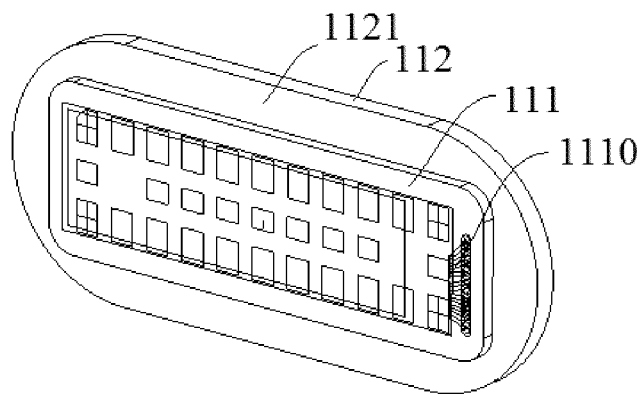


FIG. 5

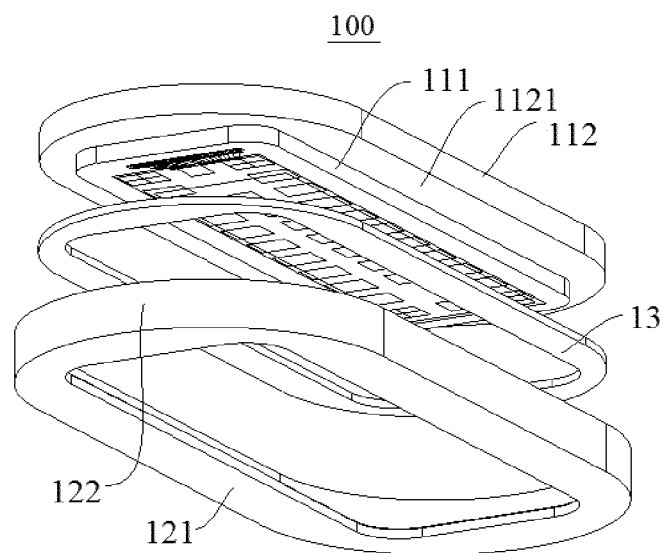


FIG. 6

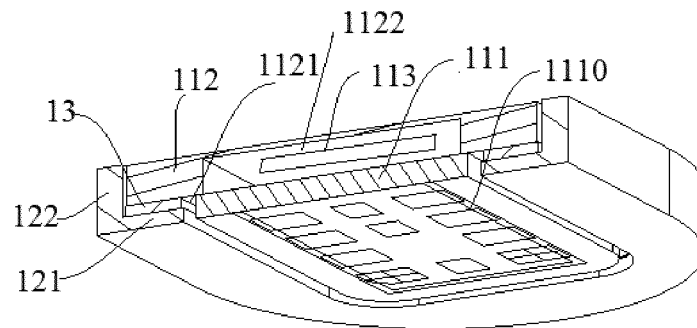


FIG. 7

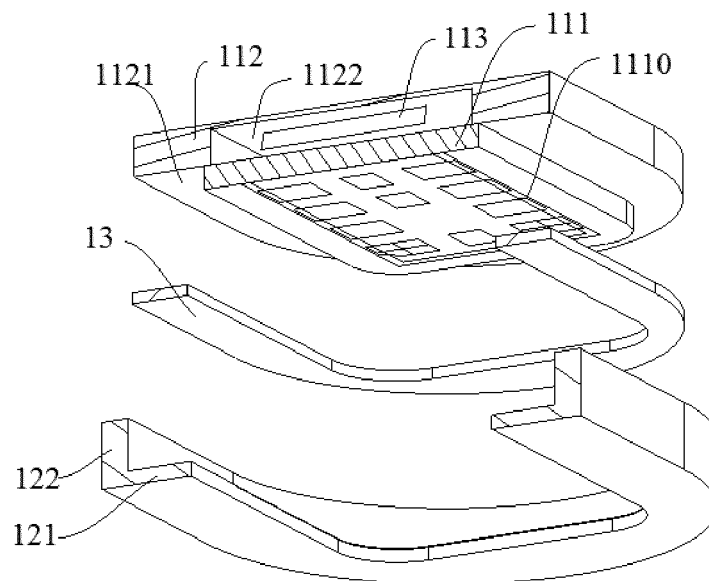


FIG. 8

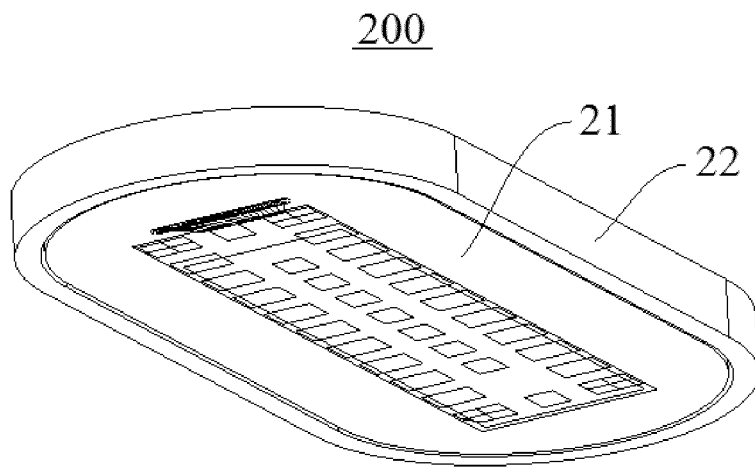


FIG. 9

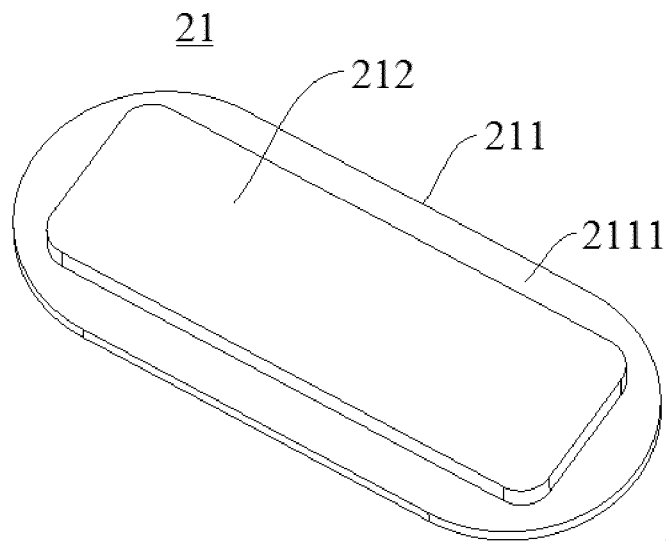


FIG. 10

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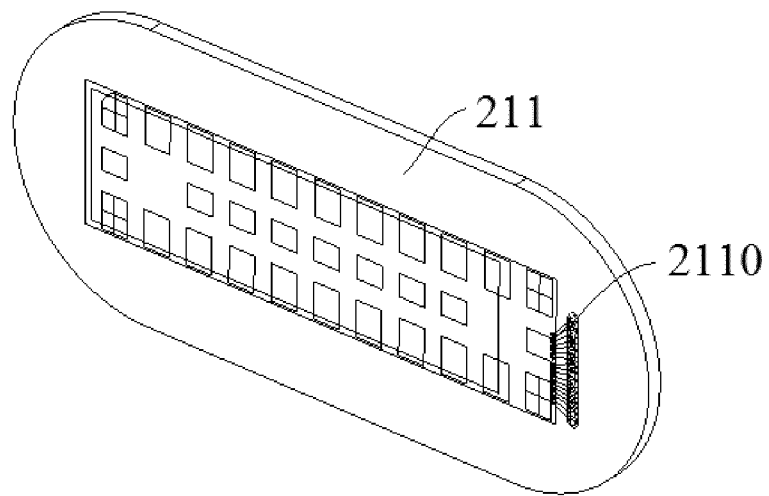


FIG. 11

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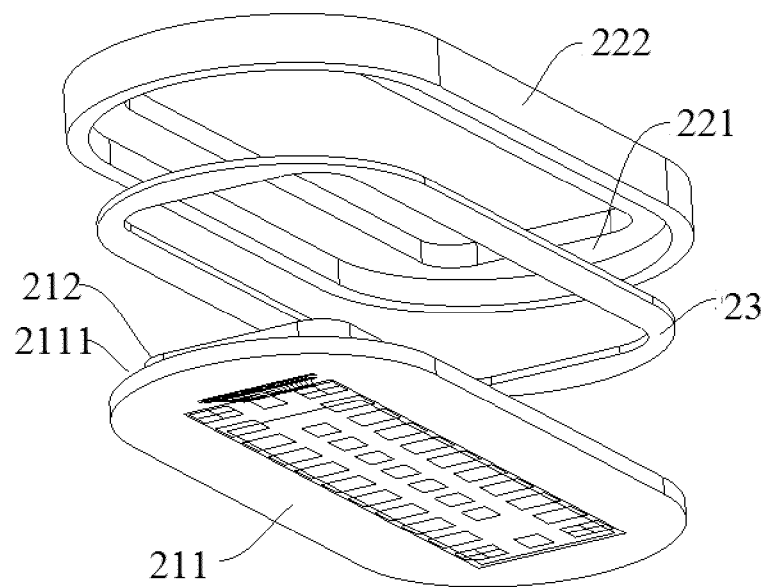


FIG. 12

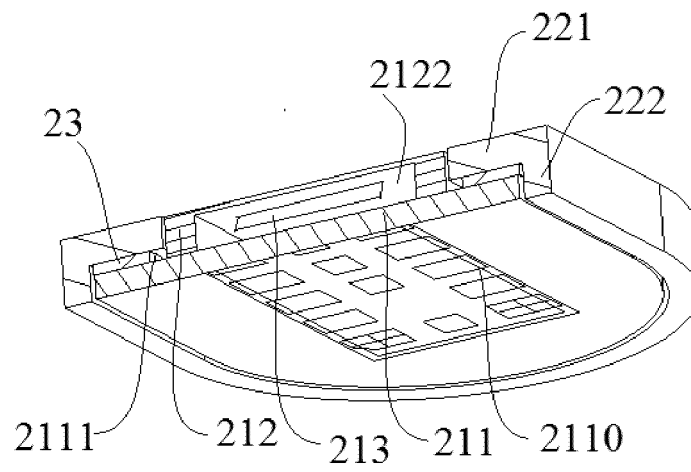


FIG. 13

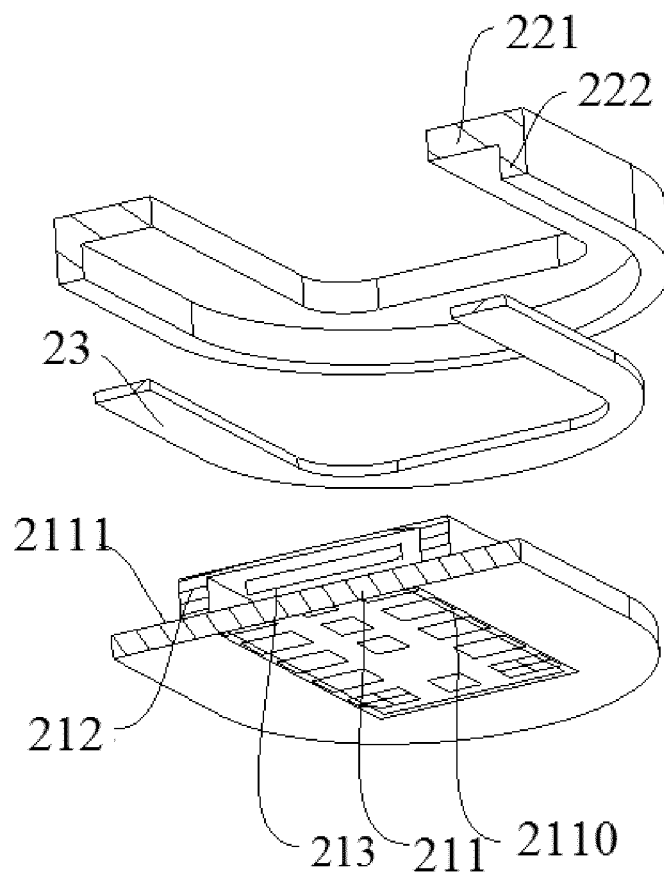


FIG. 14

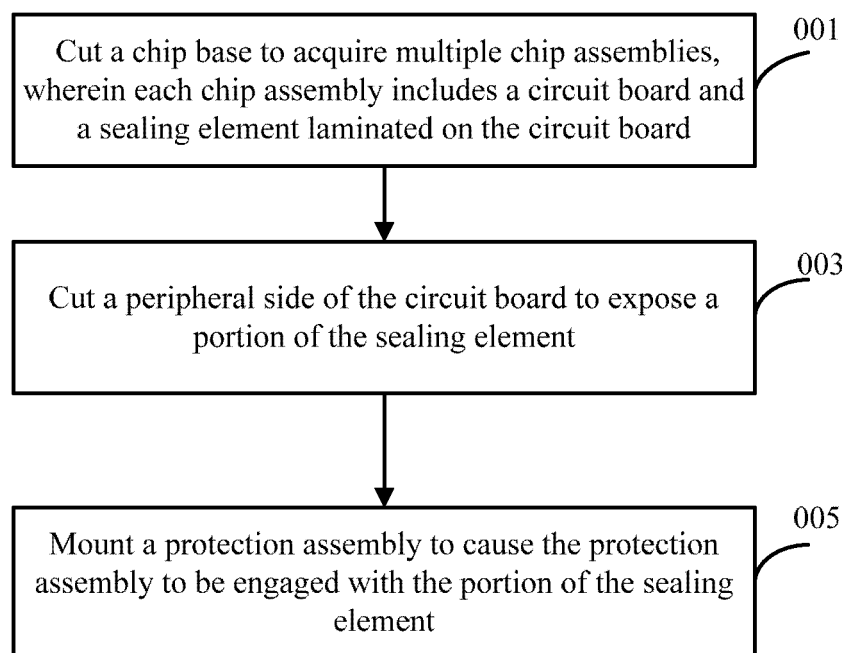


FIG. 15

REFERENCES CITED IN THE DESCRIPTION

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Patent documents cited in the description

- WO 2016036046 A1 [0003]
- DE 102013005500 A1 [0004]
- US 20110309482 A1 [0005]
- CN 105825165 A [0006]
- CN 101131945 A [0007]

专利名称(译)	指纹传感器和终端使用相同		
公开(公告)号	EP3288245B1	公开(公告)日	2019-03-06
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[标]申请(专利权)人(译)	广东欧珀移动通信有限公司		
申请(专利权)人(译)	OPPO广东移动通信CORP. , LTD.		
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[标]发明人	ZHANG WENZHEN		
发明人	ZHANG, WENZHEN		
IPC分类号	H04M1/02 A61B5/00 A61B5/117 G01B7/28 G01B11/24 G06K9/00 G06K19/08 H01L27/146 G06F1/16		
代理机构(译)	MEWBURN ELLIS LLP		
优先权	201620891207.7 2016-08-16 CN 201610677148.8 2016-08-16 CN		
其他公开文献	EP3288245A1		
外部链接	Espacenet		

摘要(译)

提供指纹传感器。指纹传感器可包括芯片组件(11)和保护元件(12)。芯片组件(11)可以包括电路板(111)和层叠在电路板(111)上的密封元件(112)。保护组件(12)可包括第一保护元件(121)。密封元件(112)与第一保护元件(121)接合以限定用于容纳电路板(111)的空间。还提供了相关终端。

